V1.0



N-Channel Super Junction Power MOSFET $\, \mathrm{I\!V} \,$

General Description

The series of devices use advanced trench gate super junction technology and design to provide excellent R_{DS(ON)} with low gate charge. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, and industrial power applications.

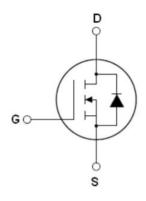
Features

- Optimized body diode reverse recovery performance
- ●Low on-resistance and low conduction losses
- Small package
- ●Ultra Low Gate Charge cause lower driving requirements
- ●100% Avalanche Tested
- ROHS compliant

Application

- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)
- LLC Half-bridge

| V _{DS min@Tjmax} | 750 | V |
|---------------------------|-----|----|
| R _{DS(ON)TYP} . | 820 | mΩ |
| I_D | 5 | Α |
| Qg | 9.7 | nC |



Schematic diagram

Package Marking And Ordering Information

| Device | Device Package | Marking | |
|------------|----------------|------------|--|
| NCE70N900K | TO-252-2L | NCE70N900K | |



TO-252

Table 1. Absolute Maximum Ratings (T_c=25℃)

| Parameter | Symbol | Value | Unit |
|-----------------------------------------------------------------|-------------------------|---------|------|
| Drain-Source Voltage (VGS=0V) | V _{DS} | 700 | V |
| Gate-Source Voltage (VDS=0V) ,AC (f>1 Hz) | Vgs | ±30 | V |
| Gate-Source Voltage (VDS=0V) ,DC | Vgs | ±20 | V |
| Continuous Drain Current at Tc=25°C | I _{D (DC)} | 5 | A |
| Continuous Drain Current at Tc=100°C | I _{D (DC)} | 3.5 | A |
| Pulsed drain current (Note 1) | I _{DM (pluse)} | 15 | A |
| Maximum Power Dissipation(Tc=25℃) | P _D | 73 | W |
| Derate above 25°C | | 0.48 | W/°C |
| Single pulse avalanche current (Note 2) | I _{AS} | 1.1 | A |
| Reverse diode dv/dt, $V_{DS} \leq 480 \text{ V,I}_{SD} < I_{D}$ | dv/dt | 15 | V/ns |
| Drain Source voltage slope,V _{DS} ≤480 V | dv/dt | 50 | V/ns |
| Operating Junction and Storage Temperature Range | T_{J},T_{STG} | -55+175 | °C |

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Table 2. Thermal Characteristic

| Parameter | Symbol | Value | Unit |
|---------------------------------------------------|-------------------|-------|-------|
| Thermal Resistance, Junction-to-Case (Maximum) | R_{thJC} | 2.05 | °C /W |
| Thermal Resistance, Junction-to-Ambient (Maximum) | R_{thJA} | 62 | °C /W |

 Table 3. Electrical Characteristics (TA=25℃unless otherwise noted)

| Parameter | Symbol | Condition | Min | Тур | Max | Unit |
|------------------------------------------|---------------------|---------------------------------------------------------|-----|------|------|------|
| On/off states | | | | | | |
| Drain-Source Breakdown Voltage | BV _{DSS} | V _{GS} =0V I _D =250uA | 700 | | | V |
| Zero Gate Voltage Drain Current(Tc=25℃) | I _{DSS} | V _{DS} =700V,V _{GS} =0V | | | 1 | μA |
| Zero Gate Voltage Drain Current(Tc=125℃) | I _{DSS} | V _{DS} =700V,V _{GS} =0V | | | 50 | μA |
| Gate-Body Leakage Current | I _{GSS} | V _{GS} =±20V,V _{DS} =0V | | | ±200 | nA |
| Gate Threshold Voltage | V _{GS(th)} | V _{DS} =V _{GS} ,I _D =250uA | 3 | | 4 | V |
| Drain-Source On-State Resistance | R _{DS(ON)} | V _{GS} =10V, I _D =2.5A | | 820 | 900 | mΩ |
| Dynamic Characteristics | | | | | | |
| Gate Resistance | Rg | F=1MHZ, D-S short | | 35 | | Ω |
| Input Capacitance | C _{lss} | V 50VV 0V | | 471 | | pF |
| Output Capacitance | Coss | $V_{DS}=50V, V_{GS}=0V,$ | | 14 | | pF |
| Reverse Transfer Capacitance | C _{rss} | F=1MHz | | 4 | | pF |
| Total Gate Charge | Qg | | | 11 | 12 | nC |
| Gate-Source Charge | Q _{gs} | V_{DS} =520V, I_{D} =2.5A, V_{GS} =10V | | 3.7 | | nC |
| Gate-Drain Charge | Q _{gd} | | | 2.7 | | nC |
| Gate plateau voltage | Vgp | | | 5.1 | | V |
| Switching times | | | | | | |
| Turn-on Delay Time | t _{d(on)} | | | 8 | | nS |
| Turn-on Rise Time | t _r | V_{DD} =520 V , I_{D} =2.5 A , | | 5 | | nS |
| Turn-Off Delay Time | t _{d(off)} | R_G =4 Ω , V_{GS} =10 V | | 50 | | nS |
| Turn-Off Fall Time | t _f | | | 9 | | nS |
| Source- Drain Diode Characteristics | | | • | | | |
| Source-drain current(Body Diode) | I _{SD} | T -25°C | | | 5 | Α |
| Pulsed-Source-drain current(Body Diode) | I _{SDM} | T _C =25°C | | | 15 | Α |
| Forward on voltage | V _{SD} | Tj=25°C,I _{SD} =5A,V _{GS} =0V | | 0.9 | 1.1 | V |
| Reverse Recovery Time | t _{rr} | | | 180 | | nS |
| Reverse Recovery Charge | Q _{rr} | Tj=25°C,I _F 2.5A, | | 0.54 | | uC |
| Peak reverse recovery current | I _{rrm} | di/dt=100A/µs | | 6 | | Α |

Notes: 1. Repetitive Rating: Pulse width limited by maximum junction temperature

2. Tj=25 $^{\circ}\text{C}$,VDD=50V,VG=10V, RG=25 Ω



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)

Figure 1. Safe operating area

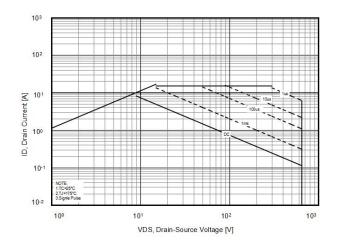


Figure 2. Source-Drain Diode Forward Voltage

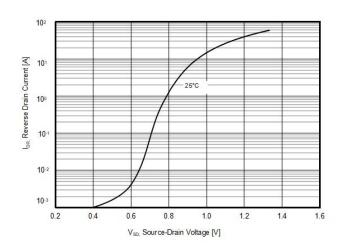


Figure 3. Output characteristics

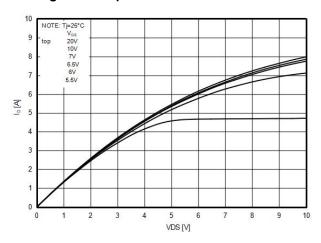


Figure 4. Transfer characteristics

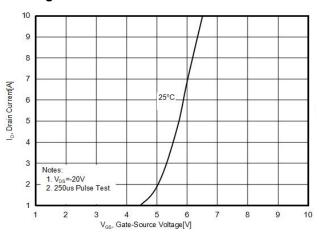


Figure 5. Static drain-source on resistance

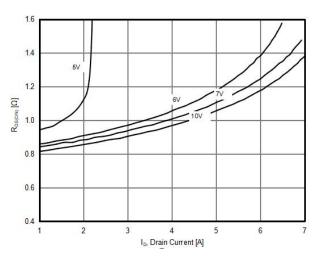


Figure 6. R_{DS(ON)} vs Junction Temperature

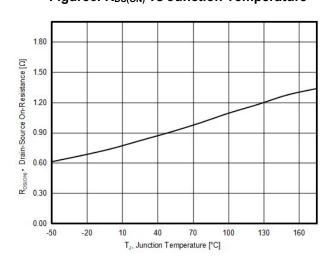




Figure 7. BV_{DSS} vs Junction Temperature

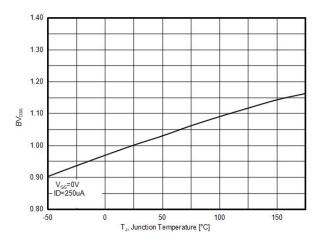


Figure 9. Gate charge waveforms

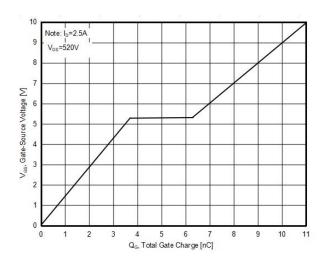


Figure 8. Maximum ID vs Junction Temperature

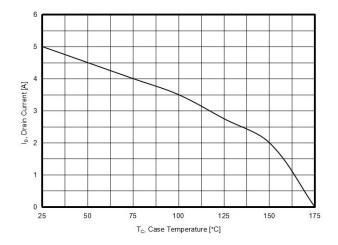
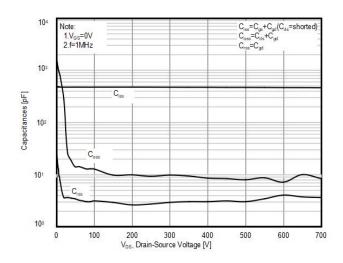


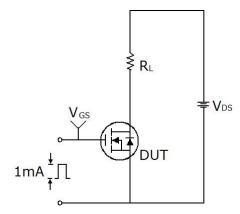
Figure 10. Capacitance

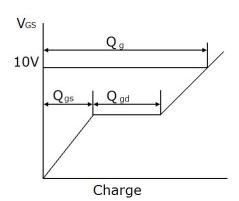




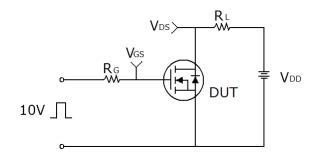
Test circuit

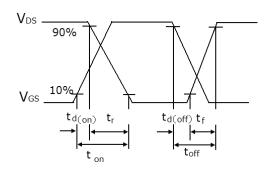
1) Gate charge test circuit & Waveform



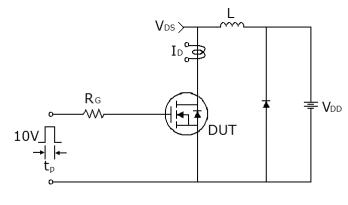


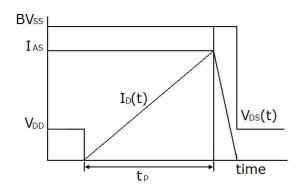
2) Switch Time Test Circuit:





3) Unclamped Inductive Switching Test Circuit & Waveforms

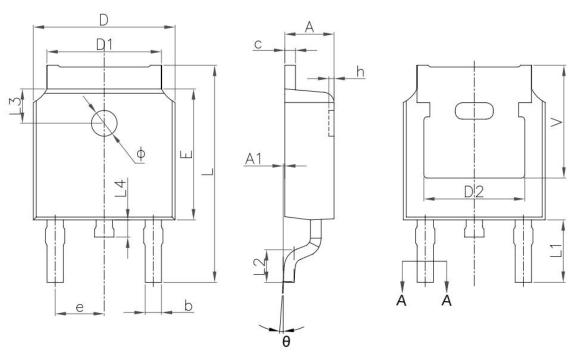




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TO-252-E Package Information



| Symbol | Dimensions | In Millimeters | Dimension | s In Inches | |
|--------|------------|----------------|-----------|-------------|--|
| | Min. | Max. | Min. | Max. | |
| Α | 2.20 | 2.40 | 0.087 | 0.094 | |
| A1 | 0.00 | 0.13 | 0.000 | 0.005 | |
| b | 0.66 | 0.83 | 0.026 | 0.033 | |
| b1 | 0.73 | 0.79 | 0.029 | 0.031 | |
| С | 0.46 | 0.58 | 0.018 | 0.023 | |
| c1 | 0.50 | 0.52 | 0.020 | 0.020 | |
| D | 6.50 | 6.70 | 0.256 | 0.264 | |
| D1 | 5.10 | 5.46 | 0.201 | 0.215 | |
| D2 | 4.83 | .83 REF 0.1 | | PREF | |
| E | 6.00 | 6.20 | 0.236 | 0.244 | |
| е | 2.19 | 2.39 | 0.086 | 0.094 | |
| L | 9.80 | 10.40 | 0.386 | 0.409 | |
| L1 | 2.90 | 2.90 REF | | REF | |
| L2 | 1.40 | 1.70 | 0.055 | | |
| L3 | 1.60 | REF | 0.06 | REF | |
| L4 | 0.60 | 1.00 | 0.024 | 0.039 | |
| Ф | 1.10 | 1.30 | 0.043 | 0.051 | |
| θ | 0° | 8° | 0° | 8° | |
| h | 0.00 | 0.30 | 0.000 | 0.012 | |



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